



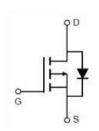
MJ P-Channel Enhancement Mode Power MOSFET

Description

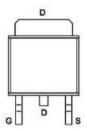
The MJ40P15K uses advanced trench technology and design to provide excellent $R_{\text{DS}(\text{ON})}$ with low gate charge . This device is well suited for use as a load switch or in PWM applications.

General Features

- $ightharpoonup V_{DS} = -40 \text{V}, I_D = -15 \text{A}$ $R_{DS(ON)} < 35 \text{m}\Omega$ @ V_{GS}=-10 V $R_{DS(ON)} < 45 \text{m}\Omega$ @ V_{GS}=-4.5 V
- ◆ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Excellent package for good heat dissipation





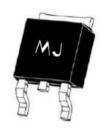


Application

Load switch

PWM application

Marking and pin assignment



TO-252-2L top view

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ40P15K	MJ40P15K	TO-252-2L	ii ii	-	2

Absolute Maximum Ratings (Tc =25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-40	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	-15	Α
Pulsed Drain Current	Ідм	-60	А
Maximum Power Dissipation	Po	50	W
Operating Junction and Storage Temperature Range	Тл ,Тѕтс	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rөjc	3.0	°C/W	





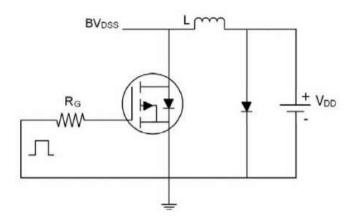
Electrical Characteristics (Tc =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			'			
Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =-40V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	,					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =-250µA	-1.0	-1.5	-2.0	V
		V _{GS} =-10V, I _D =-15A	-	29	35	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =-4.5V, I _D =-10A	-	34	45	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-15A	-	10	-	S
Dynamic Characteristics (Note 4)	1		1	1		
Input Capacitance	Ciss		-	930	-	PF
Output Capacitance	Coss	V _{DS} =-20V,V _{GS} =0V F=1.0MHz	-	85	-	PF
Reverse Transfer Capacitance	Crss	-	-	35	-	PF
Switching Characteristics (Note 4)	'					
Turn-on Delay Time	td(on)	- V - 20V D - 40	_	8	-	nS
Turn-on Rise Time	tr		-	4	-	nS
Turn-Off Delay Time	td(off)	V_{DD} =-20V, R _L =1Ω V_{GS} =-10V,R _G =3Ω	-	32	-	nS
Turn-Off Fall Time	tr	-	-	7	-	nS
Total Gate Charge	Qg		_	25	-	nC
Gate-Source Charge	Qgs	V _{DS} =-20V,I _D =-15A V _{GS} =-10V	_	3	-	nC
Gate-Drain Charge	Q _{gd}	-	_	7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =-15A	_	_	-1.2	V
Diode Forward Current (Note 2)	ls		-	-	-15	А
Reverse Recovery Time	trr	T. 05°C 1 454	_	25	_	nS
Reverse Recovery Charge	Qrr	TJ=25°C, IF=-15A di/dt=-100A/µs (Note 3)	_	31	_	nC

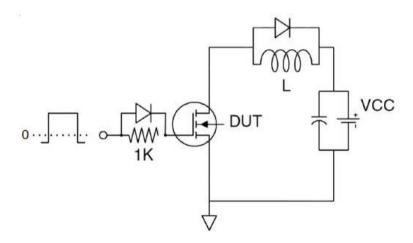
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4 Guaranteed by design, not subject to production

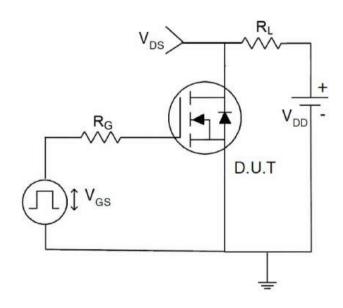
Test circuit



Eas test Circuit



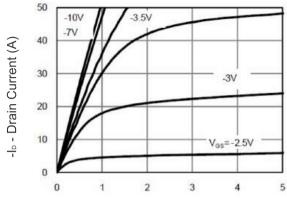
Gate charge test Circuit



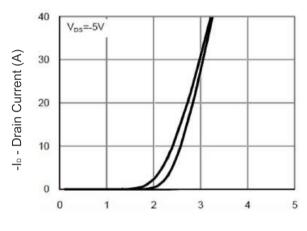
Switch Time Test Circuit



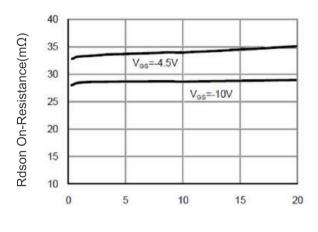
P- Channel Typical Electrical and Thermal Characteristics (Curves)



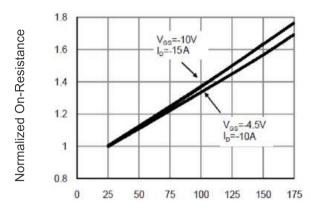




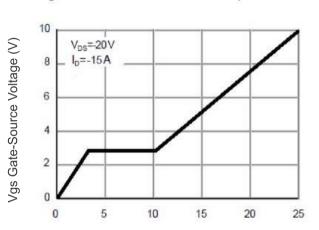
-Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics



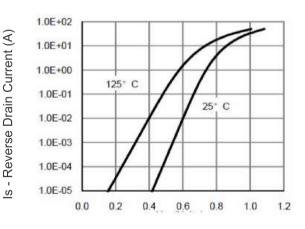
-lo - Drain Current (A)
Figure 3 Rdson- Drain Current



TJ -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)
Figure 5 Gate Charge

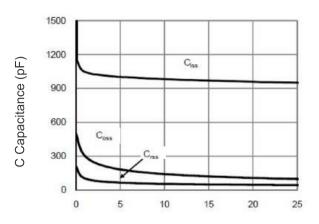


-Vsd Source-Drain Voltage (V)

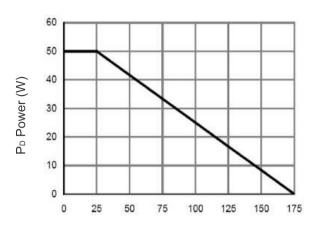
Figure 6 Source- Drain Diode Forward





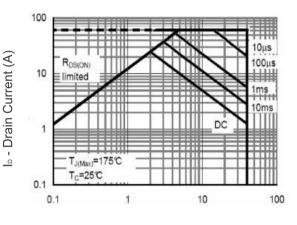


-Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds

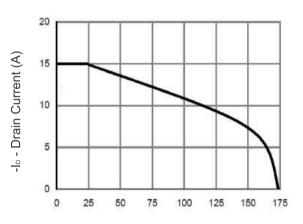


T_J -Junction Temperature(°C)

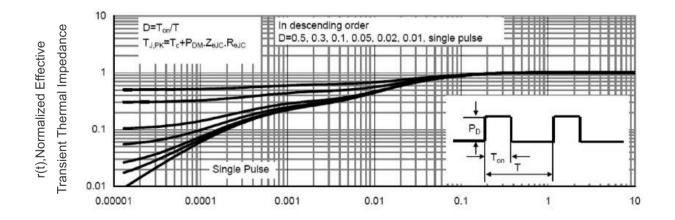
Figure 9 Power Dissipation



-Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 I_D Current De-rating



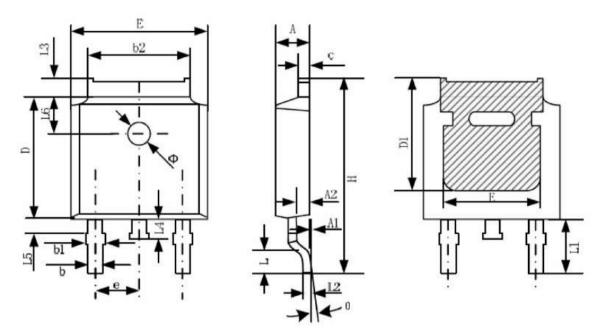
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





TO-252-2L Package Information



Cimebal	Dimensions In Millimeters		Dimension	s In Inches	
Symbol	Min.	Max.	Min.	Max.	
Α	2.20	2.38	0.087	0.094	
A1	0.00	0.10	0.000	0.004	
A2	0.90	1.10	0.035	0.043	
b	0.72	0.85	0.028	0.033	
b1	0.72	0.90	0.028	0.035	
b2	5.13	5.46	0.202	0.215	
С	0.47	0.60	0.019	0.024	
D	6.00	6.20	0.236	0.244	
D1	5.25		0.207	-	
E	6.50	6.70	0.256	0.264	
E1	4.70	12	0.185	_	
e	2.19	2.39	0.086	0.094	
Н	9.80	10.40	0.386	0.409	
L	1.40	1.70	0.055	0.067	
L1	2.90	REF	0.114	4 REF	
L2	0.508 BSC		0.020	BSC	
L3	0.90	1.25	0.035	0.049	
L4	0.60	1.00	0.024	0.039	
L5	0.15	0.75	0.006	0.030	
L6	1.80	REF	0.071 REF		
Φ	1.20	1.40	0.047	0.055	
0	0°	8°	0°	8°	





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